

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 08/25/2022

Details for "CD74HC574M96"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
CD74HC574M96	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DW 20	7.52x12.82x2.35	612.6

*Total Device Mass
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component			Substance		CAS Number		Amount (mg)		Homogeneous Material Level		Component Level	
									Percentage %		ppm	
Bond Wire												
Copper and Its Alloys			Copper	7440-50-8			0.101056		99.99901		999990	
Precious Metals			Silver	7440-22-4			0.000001		0.00099		10	
Sub-Total							0.101057		100		1000000	
Die Attach Adhesive												
Precious Metals			Silver	7440-22-4			0.361207		79.999956		800000	
Thermoplastics			Epoxy	85954-11-6			0.090302		20.000044		200000	
Sub-Total							0.451509		100		1000000	
Lead Frame												
Copper and Its Alloys			Copper	7440-50-8			166.063322		97.585		975850	
Copper and Its Alloys			Iron	7439-89-6			3.913979		2.3		23000	
Copper and Its Alloys			Phosphorus	7723-14-0			0.025526		0.015		150	
Zinc and Its Alloys			Zinc	7440-66-6			0.170173		0.1		1000	
Sub-Total							170.173		100		1000000	
Lead Frame Plating												
Nickel and Its Alloys			Nickel	7440-02-0			0.313896		95.12		951200	
Precious Metals			Gold	7440-57-5			0.002574		0.78		7800	
Precious Metals			Palladium	7440-05-3			0.01353		4.1		41000	
Sub-Total							0.33		100		1000000	
Mold Compound												
Other Inorganic Materials			Fused Silica	60676-86-0			387.282181		88		880000	
Other Plastics and Rubber			Carbon Black	1333-86-4			1.32028		0.3		3000	
Other Plastics and Rubber			Organic Phosphorus	1330-78-5			2.420514		0.55		5500	
Thermoplastics			Epoxy	85954-11-6			49.070413		11.15		111500	
Sub-Total							440.093388		100		1000000	
Semiconductor Device												
Ceramics / Glass			Doped Silicon	7440-21-3			1.477723		100		1000000	
Sub-Total							1.477723		100		1000000	
Total							612.626677				100	

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products
TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.